

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Mark Moshayed) Group Art Unit 2811
App. No. : 09/514,633)
Filed : February 28, 2000)
For : APPARATUS FOR STACKING)
SEMICONDUCTOR CHIPS)
Examiner : Jhihan B. Clark)

#2

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Enclosed is form PTO-1449 listing references that are also enclosed. This Information Disclosure Statement is being filed before the receipt of a first Office Action on the merits, and presumably no fee is required in accordance with 37 C.F.R. § 1.97(b)(3). If a first Office Action on the merits was mailed before the mailing date of this Statement, the Commissioner is authorized to charge the fee set forth in 37 C.F.R. § 1.17(p) to Deposit Account No. 11-1410. A duplicate copy of this Statement is enclosed for that purpose.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 3/21/01

By: John R. King
John R. King
Registration No. 34,362
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Sixteenth Floor
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(949) 760-0404

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| FORM PTO-1449 | U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | ATTY. DOCKET NO. SIMTECH.088RAC | APPLICATION NO. 09/514,633 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT (USE SEVERAL SHEETS IF NECESSARY) | | APPLICANT Mark Moshayedi | |
| | | FILING DATE February 28, 2000 | GROUP 2811 |

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| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE (IF APPROPRIATE) |
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| *EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT. | |

FORM PTO-1449

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